

TP080 Series Thermally Conductive Gap Filler

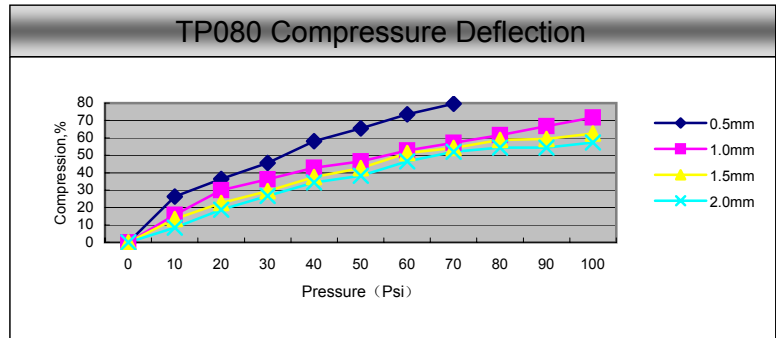
Thermal Interface Materials

Features:

- 0.8W/m.k thermal conductivity
- High conformability and cost effective
- Naturally tacky
- Electrically insulating

Applications:

- Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.
- Led Lighting, Solar Panel, Telecom device, wireless Hub, Battery, power supply etc
- Cooling Module, Memory modules



Typical Properties of TP080

Properties	Units	TP080	Test Method
Construction & Composition	----	Silicone & Ceramic filled	----
Color	----	Gray	Visual
Thickness Range	mm	0.5~12.0	----
Hardness	Shore C	35	ASTM D2240
Density	g/cc	2.0	ASTM D792
Tensile Strength	KN/m	1.3	ASTM D412
Elongation	%	1.35	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥4.0	ASTM D149
Volume Impedance	ohm-cm	1.7×10^{16}	ASTM D257
Dielectric Constant	1MHz	4.51	ASTM D150
Weight Damnify	----	≤1 %	@150°C 240H
Flame Rating	----	V0	UL 94
Thermal Conductivity	W/m.k	0.8	ASTM E1461
UL, RoHS, REACH	----	Compliance	----

Sheet sizes:

Standard sheet size:200x400mm, 330x330mm; Custom Die-cut parts available; Available with or without PSA

Any information contained herein is believed to be accurate and reliable. AOK and its agents does not assume any responsibility or liability for any advice furnished by it, or for the performance or results of any installation or use of the product(s) or of any final products into which the product(s) may be incorporated by the purchaser and/or user. The purchaser and/or user should perform its own tests to determine the suitability and fitness of the product (s) for the particular purpose desired in any given situation.